L Number	Hits	Search Text	DB	Time stamp
-	4	(("4340462") or ("5262029") or ("5437757") or ("5656122") or ("61566276")).PN.	USPAT; US-PGPUB	2002/03/28 09:36
-	5	(("4340462") or ("5262029") or ("5437757") or ("5656122") or ("6156276")).PN.	USPAT; US-PGPUB	2002/03/26 10:58
-	5	(("4340462") or ("5262029") or ("5437757") or ("5656122") or ("6165276")).PN.	USPAT; US-PGPUB	2002/03/26 11:01
-	3091	(118/715,724,725).CCLS.	USPAT; US-PGPUB	2002/03/28 10:30
-	32	((118/715,724,725).CCLS.) and (clamp same heat$3 same (gas with (purge purging backside clean cleaning)))	USPAT; US-PGPUB	2002/03/28 16:06
-	7	5882419.URPN.	USPAT	2002/03/26 11:48
-	14	((118/715,724,725).CCLS.) and (((clean cleaning) with gas) same clamp)	USPAT; US-PGPUB	2002/03/26 13:12
-	0	((118/715,724,725).CCLS.) and ("backside gas" with clean)	USPAT; US-PGPUB	2002/03/26 13:13
-	18	((118/715,724,725).CCLS.) and ("purge gas" with clean)	USPAT; US-PGPUB	2002/03/26 13:59
-	2	((118/715,724,725).CCLS.) and (clamp same "cleaning gas")	USPAT; US-PGPUB	2002/03/26 14:02
-	11	("4146774" | "4592924" | "4923715" | "5000113" | "5201990" | "5254171" | "5366585" | "5482749" | "5578131" | "5616208" | "5833854").PN.	USPAT	2002/03/26 14:00
-	2	((118/715,724,725).CCLS.) and ("cleaning gas" and ("cl2" "clf3"))	USPAT; US-PGPUB	2002/03/26 14:11
-	3	("5680013" | "5788799" | "5886863").PN.	USPAT	2002/03/26 14:08
-	40	((118/715,724,725).CCLS.) and ("cleaning gas" with (wafer substrate))	USPAT; US-PGPUB	2002/03/26 15:19
-	1467	"purge gas" and clean	USPAT; US-PGPUB	2002/03/26 14:51
-	2	("purge gas" with clean) and "wafer clamp"	USPAT; US-PGPUB	2002/03/26 15:18
-	14	"cleaning gas" with "purge gas"	USPAT; US-PGPUB	2002/03/26 15:22
-	345	ries.in.	USPAT; US-PGPUB	2002/03/26 15:55
-	6	ries.in. and wafer	USPAT; US-PGPUB	2002/03/26 15:55
-	7	((118/715,724,725).CCLS.) and (edge with gas with remove)	USPAT; US-PGPUB	2002/03/26 16:19
-	5	((118/715,724,725).CCLS.) and (edge with gas with clean)	USPAT; US-PGPUB	2002/03/26 16:29
-	40	((118/715,724,725).CCLS.) and ("backside gas")	USPAT; US-PGPUB	2002/03/26 16:36
-	0	"purge gas" with etch with edge	USPAT; US-PGPUB	2002/03/26 16:37
-	102	("gas" with etch with edge)	USPAT; US-PGPUB	2002/03/26 16:50
-	22	(substrate wafer) with clean with edges with gas	USPAT; US-PGPUB	2002/03/26 16:51
-	360	((118/715,724,725).CCLS.) and (heat same (susceptor holder table support)) and (heat same (clamp ring))	USPAT; US-PGPUB	2002/03/26 17:18
-	65	((118/715,724,725).CCLS.) and (heat same (susceptor holder table support)) and (heat same (clamp))	USPAT; US-PGPUB	2002/03/26 17:19
-	193	((118/715,724,725).CCLS.) and (heat with(susceptor holder table support)) and (heat with (ring clamp))	USPAT; US-PGPUB	2002/03/26 17:21
-	28	((118/715,724,725).CCLS.) and (heat with(susceptor holder table support)) and (heat with (clamp))	USPAT; US-PGPUB	2002/03/26 17:52
-	800	((118/715,724,725).CCLS.) and (heat with(susceptor holder table support))	USPAT; US-PGPUB	2002/03/26 17:33
-	45	((118/715,724,725).CCLS.) and (heat with (clamp))	USPAT; US-PGPUB	2002/03/26 18:11
-	461	118/724,725.ccls. and (heat with wall)	USPAT; US-PGPUB	2002/03/26 18:12
-	4	("purge gas" or "backside gas") with (effect adj3 deposition)	USPAT; US-PGPUB	2002/03/27 14:50

-	166	("purge gas" or "backside gas") with (composition)	USPAT; US-PGPUB	2002/03/27 15:48
-	18	"asm" with "epsilon"	USPAT; US-PGPUB	2002/03/28 09:56
-	0	("asm" with "epsilon") same purge	USPAT; US-PGPUB	2002/03/28 09:56
-	37897	h01l021$.ipc.	USPAT; US-PGPUB	2002/03/28 10:04
-	4653	c23c016$.ipc.	USPAT; US-PGPUB	2002/03/28 10:04
-	653901	h01l021$.ipc.	JPO; DERWENT	2002/03/28 10:08
-	38290	c23c016$.ipc.	JPO; DERWENT	2002/03/28 10:08
-	14	(h01l021$.ipc. or c23c016$.ipc.) and ("purge gas" with (composition or compose or composed))	JPO; DERWENT	2002/03/28 10:14
-	25	(h01l021$.ipc. or c23c016$.ipc.) and ("purge gas" with (comprise$3))	JPO; DERWENT	2002/03/28 10:28
-	8	"purge gas" with (similar)	JPO; DERWENT	2002/03/28 10:29
-	3091	(118/715,724,725).CCLS.	USPAT; US-PGPUB	2002/03/28 10:30
-	350	((118/715,724,725).CCLS.) and (heater with (two second))	USPAT; US-PGPUB	2002/03/28 10:32
-	33	((118/715,724,725).CCLS.) and (heater adj (two second))	USPAT; US-PGPUB	2002/03/28 12:24
-	44	5179677.URPN.	USPAT	2002/03/28 12:05
-	13	((118/715,724,725).CCLS.) and ((table susceptor support) with heat with mount)	USPAT; US-PGPUB	2002/03/28 12:31
-	345	ries.in.	USPAT; US-PGPUB	2002/03/28 12:32
-	26	ries.in. and (silicon wafer cvd)	USPAT; US-PGPUB	2002/03/28 12:32
-	1	ries.in. and ("purge gas" with "composition")	USPAT; US-PGPUB	2002/03/28 12:35
-	854	"ti/tin"	USPAT; US-PGPUB	2002/03/28 16:53
-	47	"ti/tin" with (results properties)	USPAT; US-PGPUB	2002/03/28 17:00
-	3	"ti/tin" with (benefit)	USPAT; US-PGPUB	2002/03/28 17:00